

Title (en)  
VERTICALLY INTEGRATED SEMICONDUCTOR SYSTEM

Title (de)  
VERTIKAL INTEGRIERTE HALBLEITERANORDNUNG

Title (fr)  
ENSEMBLE SEMI-CONDUCTEUR INTEGRE VERTICALEMENT

Publication  
**EP 1145315 A1 20011017 (DE)**

Application  
**EP 99964451 A 19991221**

Priority  
• DE 9904056 W 19991221  
• DE 19860819 A 19981230

Abstract (en)  
[origin: WO0041241A1] The invention relates to a semiconductor system which comprises at least one semiconductor chip having a first and a second main side. Said first and second main sides are provided with active structures that are connected to each other by means of interconnections passing through the semiconductor chip. The at least one semiconductor chip is arranged such that one of its main sides rests on a first main side of a support.

IPC 1-7  
**H01L 25/065**; **H01L 23/48**

IPC 8 full level  
**H01L 23/48** (2006.01); **H01L 25/065** (2006.01); **H01L 25/07** (2006.01); **H01L 25/18** (2006.01)

CPC (source: EP KR US)  
**H01L 23/481** (2013.01 - EP US); **H01L 25/04** (2013.01 - KR); **H01L 25/0657** (2013.01 - EP US); **H01L 2225/06517** (2013.01 - EP US); **H01L 2225/06541** (2013.01 - EP US); **H01L 2225/06555** (2013.01 - EP US); **H01L 2225/06572** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Citation (search report)  
See references of WO 0041241A1

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)  
**WO 0041241 A1 20000713**; BR 9916684 A 20010925; CN 1332888 A 20020123; EP 1145315 A1 20011017; JP 2002534809 A 20021015; KR 20010104320 A 20011124; RU 2213391 C2 20030927; US 2002003297 A1 20020110; US 6388320 B2 20020514

DOCDB simple family (application)  
**DE 9904056 W 19991221**; BR 9916684 A 19991221; CN 99815360 A 19991221; EP 99964451 A 19991221; JP 2000592882 A 19991221; KR 20017008283 A 20010628; RU 2001121149 A 19991221; US 89727801 A 20010702